## **OBSOLESCENCE SOLUTIONS**

KANAKA

Manufacturers	Products	Applications
CORFIN INDUSTRIES	Robotic Hot Solder Dip – Compliance with RoHS directive Component Obsolescence Challenges, Non-availability of tin-lead components, Life-time buy opportunity (Long Term Packaging), BGA Reballing for the Conversion of tin-lead, Component Harvesting, Lead Reconditioning, Lead Attach, Forming and Cutting of Pins, Elimination of Tin-Whiskers through tin-lead-alloy, grid failure <1%	Aerospace, Defense, Implantable Medical Industry, Transportation
	New Certifification: Nadcap AC7120/11	
	DATEL products are guaranteed to be available for long-term programs, Form-Fit-Function guaranteed for obsolete products, System in a Package (SIP) Technology is a Multi-Chip Module to improve performance and/or reliability while reducing size, Legacy 24 Bit Sampling A/D-Converters, 16 Bit D/A-Converters, Amplifiers, Multi-Channel Converters – Hybrid Data Acquisition Systems, Obsolete component replacement, Reverse Engineering, Process Porting & Device Replication, Custom solutions, low-volume & high-volume applications. RoHS and Non-RoHS versions available	Medical Industry, Industrial, Scientific, Military, Airborne, Aerospace
NETSOL	High Speed - Low Latency - Low Power Consumption Memory Technology, SLC NAND Flash, SPI NAND Flash, Asynchronous Low Power SRAM, Asynchronous Fast SRAM, Synchronous SRAM, Quadruple SRAM, DDR SRAM, QDR SRAM, small footprint, long-term Support	Tele-Communication, IoT, Industrial Equipment, Mobile Applications, Low Power Consumption, Medical Equipment, Smart Home, Factory Automation
TELEDYNE @2V Everywhereyoulook	Discontinued and End of Life industrial and military parts QML Class Q and Class V certified manufacturer, MIL-PRF-38535, MIL-STD-883 Analog & Interface ICs: Amplifiers, A/D- & D/A-Converters Memories: EPROMs, EEPROMs, SRAMs, CPLD Dual Port RAMs, Programmable & Discrete Logic ICs, FIFOs, Wafer & Bare Die Banking, Components Up-Screening Program	High End Industry, Aerospace, Defense, Transportation
	Custom solutions for mitigating Device Obsolescence and Board Re-Design Adapter Products, 1:1 Footprint Conversion, ASIC / FPGA Adapters to include code reconstruction and re-targeting, Interconnect Pitch Adapters, Programming Adapter Functionality Upgrade, Production & Test Sockets, Atmel AVR Adapters for µC, Reverse Engineering of Small Plastic & Metal Parts	Adapter Solutions, Device Specific Package Conversion
Xsis	High Reliability Hybrid Microcircuit Crystal Oscillators & Crystal Units Crystal Oscillators: Standard, Military, High Temperature up to +230°C, QPL M55310 Crystal Units: QPL Crystal Units, Custom Crystal Units Obsolete Through Hole packages, High Shock & Vibration Designs, Custom Solutions, Up-Screening Program	Military, High Reliability Industrial & Telecommu- nications, Defense, Space, Aircraft, High Temperature